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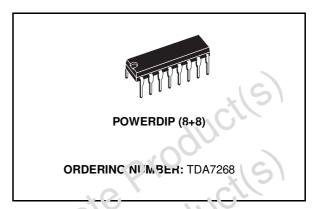


## 2 x 2W STEREO AUDIO AMPLIFIER

- WIDE OPERATING RANGE FROM 4.5V TO 18V
- $P_{OUT} = 2W @ THD 10\% 12V/8\Omega$
- INTERNAL FIXED GAIN 32dB
- NO FEEDBACK CAPACITOR
- NO BOUCHEROT CELL
- THERMAL PROTECTION
- AC SHORT CIRCUIT PROTECTION
- SVR CAPACITOR FOR BETTER RIPPLE REJECTION
- LOW TURN-ON/OFF POP
- VERY FEW EXTERNAL COMPONENTS
- STAND-BY MODE (I<sub>ST-BY</sub> < 300µA)



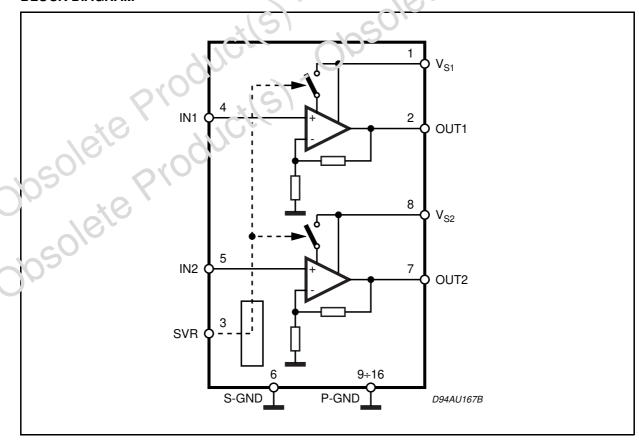
The device TDA7268 is a new technology stereo Audio Amplifier in DIP package specially de-



signed for TV application.

Thanks to the fully complementary output configuration the device delivers a rail to rail voltage awing without need of boostrap capacitor.

#### **BLOCK DIAGRAM**

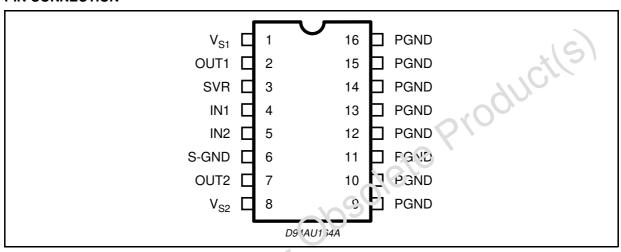


September 2003

#### **ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
Vs	Operating Supply Voltage	18	V
Io	Output Peak Current	1.5	Α
T <sub>op</sub>	Operating Temperature Range	0 to 70	°C
Tj	Junction Temperature	150	°C
T <sub>stg</sub>	Storage Temperature Range	-40 to 125	°C

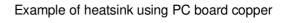
#### **PIN CONNECTION**

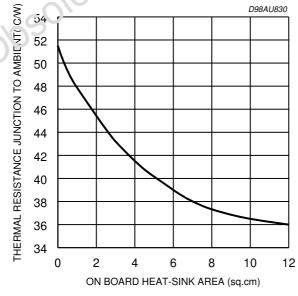


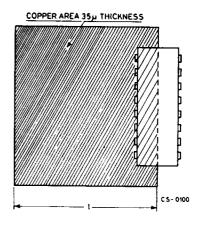
#### **THERMAL DATA**

Symbol	Parameter	Value	Unit	
R <sub>th j-amb</sub>	Thermal Resistance Junction to ambient (on PCB)	Max.	70	°C/W
R <sub>th j-case</sub>	Thermal Resistance Junction to case	Max.	15	°C/W

Rth with "on Brood" Square Heat Sink vs. Copper Area







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### **ELECTRICAL CHARACTERISTICS** ( $T_{amb} = 25^{\circ}C$ ; $V_{S} = 12V$ ; $R_{L} = 8\Omega$ ; f = 1KHz; unless otherwise specified.)

$V_S$	Parameter	Test Condition	Min.	Тур.	Max.	Unit
- 0	Supply Voltage Range		4.5		18	V
Is	Quiescent Current	ent Current		40	60	mA
I <sub>sb</sub>	Stand-By Current Pin 3 shorted to GND			0.15	0.3	mA
Vo	Quiescent Output Voltage		5.5	6	6.5	V
$A_V$	Voltage Gain		31	32	33	dB
$\Delta A_V$	Voltage Gain Matching				1.0	dB
$R_{IN}$	Input Impedance			100		KΩ
Po	Output Power	THD = 10%	1.9	2		W
THD	Distortion	P <sub>O</sub> = 1W		0.1	0.4	%
SVR	Supply Voltage Rejection	$\begin{array}{l} V_{rip.} = 150 mVrms;  F_{rip.} = 1 KHz \\ R_S = 10 k\Omega \\ R_S = 50 \Omega \end{array}$	40	50 46	115	d3 dB
en	Total Input Noise Voltage	Rg = $10K\Omega$ ; BW = $20Hz$ to $20KHz$		11	8	μV
CT	Cross Talk	P <sub>O</sub> = 1W;	50	30	ĺ	dB
V <sub>sb</sub>	Stand-By Enable Voltage	I <sub>SB</sub> < 300μA	201	$\bigcirc$	1	V
A <sub>sb</sub>	Stand-By Attenution		60	80		dB
Po	Output Power	THD = 10%; $V_S = 9V$ ; $R_L = {}^{1}\Omega$		1.8		W
		1050				
,501E	ate Productl	THD = 10%; V <sub>S</sub> = 9V; R <sub>L</sub> = · · s <sub>L</sub>				

Fig. 1: Standard Test and Application Circuit

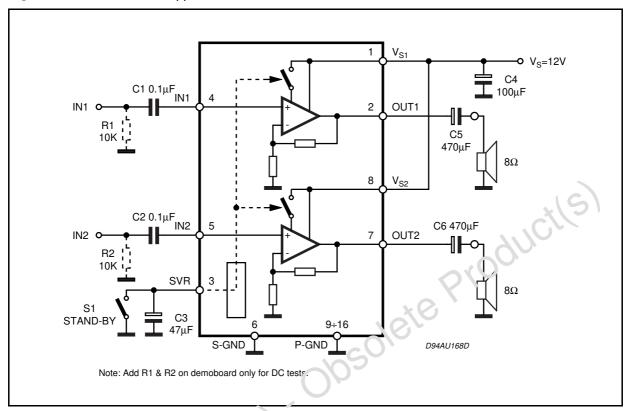
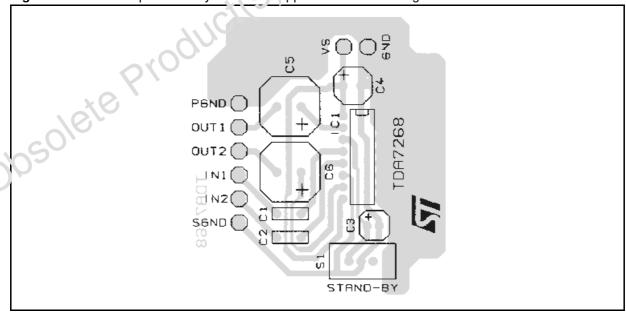


Fig. 2: PCB And Components Layout ()f the Application Circuit of Figure 1



#### **APPLICATION HINTS:**

For 12V supply and  $8\Omega$  speaker application, its maximum power dissipation is about 2W.

Assumming that max ambient temperature is 70°C. Required thermal resistance of the device and heat dissipating means must be equal to (150

 $-70)/2 = 40^{\circ}$ C/W.

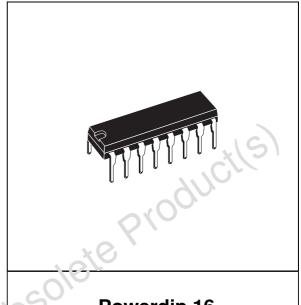
Junction to pin thermal resistance of the package is about 15°C/W.

That means external heat sink of about  $25^{\circ}\text{C/W}$  is required. Stand-By switches must be able to discharge  $C_{\text{SVr}}$  current.

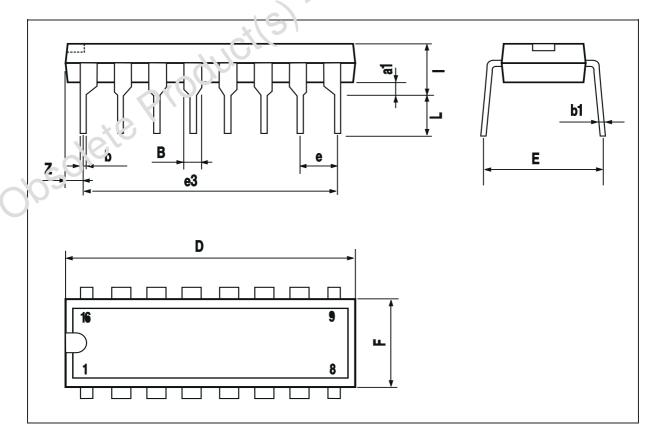
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DIM.	mm			inch			
<b>D</b>	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
a1	0.51			0.020			
В	0.85		1.40	0.033		0.055	
b		0.50			0.020		
b1	0.38		0.50	0.015		0.020	
D			20.0			0.787	
E		8.80			0.346		
е		2.54			0.100		
e3		17.78			0.700		
F			7.10			0.280	
I			5.10			0.201	
L		3.30			0.130		
Z			1.27			0.050	

# OUTLINE AND MECHANICAL DATA



Powerdip 16



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